XL-IR

目录

Catalog

电性参数
Electrical Characteristics.....3

典型特性曲线
Typical Characteristic Curves.....7

可靠性实验
Reliability Test Items And Conditions.....8

外形尺寸
Outline Dimensions.....9

包装
Packaging.....10

使用注意事项
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电性参数

Electrical Characteristics

Absolute Maximum Ratings Ta=25

Parameter	Symbol	Rating	Unit
Supply Voltage	VDD	6.0	V
Operating ambient temperature	Topr	-20 C ~ +85 C	
Storage ambient temperature	Tstg	-40 C ~ +125 C	
Welding conditions	Tsol	Wave soldering 260℃ 6s manual welding 300℃ 3s	

Initial Electrical Optical Characteristics Ta=25

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Working current	ICC	0.3	0.4	0.5	mA	VDD=5V
receive distance	L 0 °	10	15	-	M	/
	L 35 °	5	6	-	M	
	L 35 °	5	6	-	M	
Carrier Frequency	f_o	-	37.9	-	KHZ	/
BPF BPF width	f_{BW}	-	6	-	KHZ	/
Low level output	V_{ol}	-	-	250	mV	Isink=2.0mA
High level output	V_{oh}	4.5	-	5.0	V	VCC=5V
Pulse width	T_{pwl}	400	600	800	us	burst wave Vin=500UVp-p
	T_{PWH}	400	640	800	us	burst wave Vin=50mVp-p

Recommended usage conditions

Parameter	Symbol	Min.	Ÿ ı è

接收距离分档:

Receive distance grading

代码 Code	最小值 Min	最大值 Max	单位 Unit	测试条件 Test conditions
L1	6	8	M	ICC=0.5mA
L2	10	15		
L3	15	20		

工作电压分档

Working voltage grading

代码 Code	最小值 Min	最大值 Max	单位 Unit	测试条件 Test conditions
V1	2.5	5.5	V	ICC=0.5mA
V2	2.7	5.5		

工作电流分档:

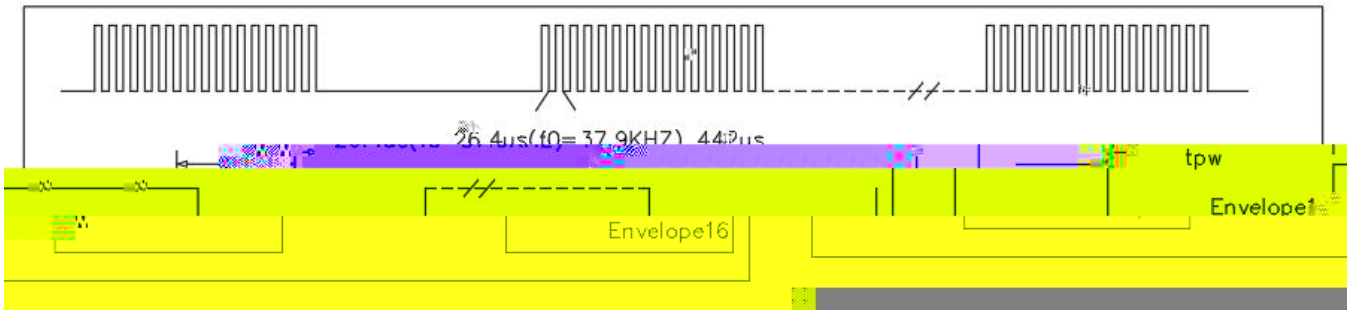
Working current grading

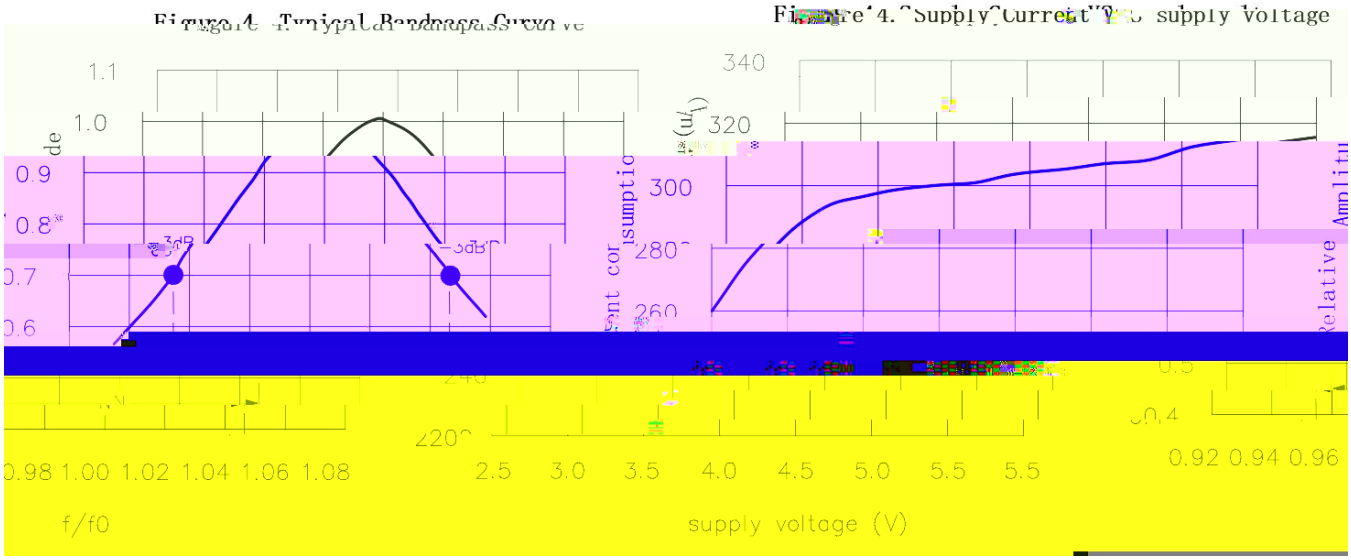
代码 Code	最小值 Min	最大值 Max	单位 Unit	测试条件 Test conditions
I1	0.3	0.5	mA	VDD=5V
I2	0.4	0.7		

典型特性曲线

Typical Characteristics Curves

Test waveform





可靠性试验

Reliability Test Items And Conditions

*	Reliability Test Proje		
	260 ±5	5	20
	100PF 1.5KΩ, 4KV,		20

焊接(1)

Guideline for Soldering (1)

1. 使用烙铁人手焊接

Hand Soldering

30W

300 3

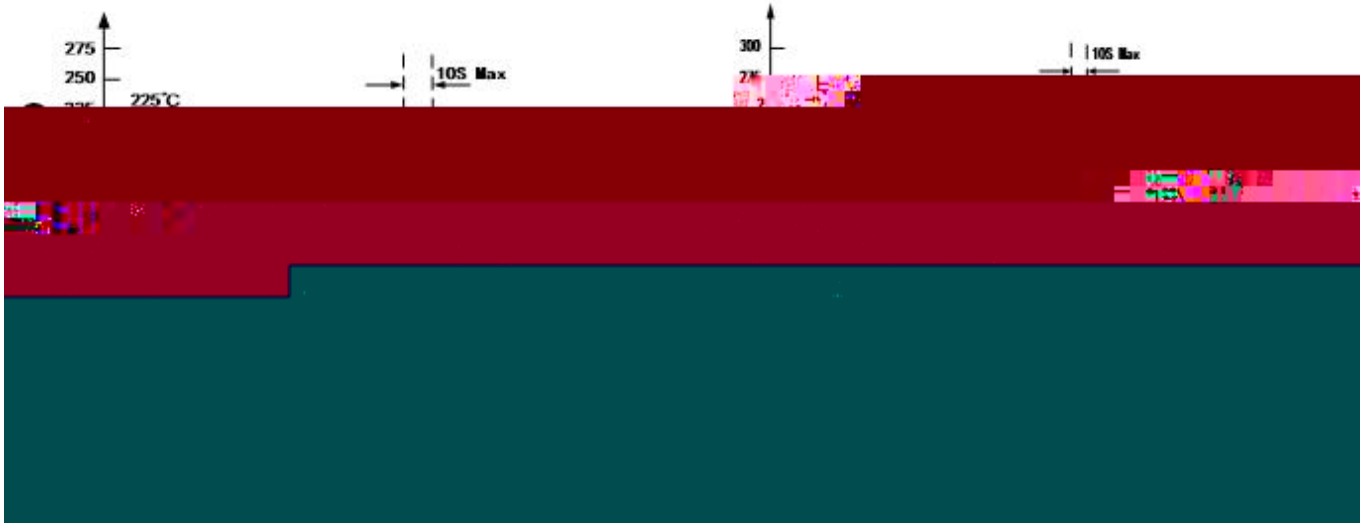
LED

Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300 while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is often started at the time of the hand soldering.

2. 回流焊接：

Reflow Soldering: Use the conditions shown in the under Figure ofPb-Free Reflow Soldering.



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Reflow soldering should not be done more than two times.

. LED

Stress on the LEDs should be avoided during heating in soldering process.

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After soldering, do not deal with the product before its temperature drop down to room

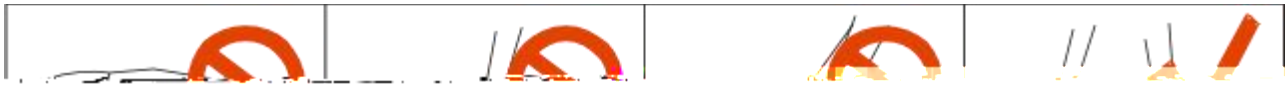
焊接指导（2

使用注意事项：

Applications (3)

Others

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with the